

## ABSTRACT OF THE DISCLOSURE

~~[OBJECT]~~—~~To improve~~The invention can provide an improvement in the  
connection reliability in mounting semiconductor chips.

~~[MEANS FOR SOLUTION]~~—~~Solder~~The invention can include solder balls 6~~that~~ are disposed  
on a back surface of an interposer substrate-1, in a manner to avoid diagonal lines 7 of the  
interposer substrate-1, and a semiconductor chip 3 is mounted on a surface of the interposer  
substrate-1. The invention permits electronic devices to be made that are smaller and lighter,  
while improving their reliability.